

a plurality of conductive leads inserted through the peripheral side wall and the inner wall.

48. (New) The semiconductor die carrier according to claim 47, further comprising a cavity extending between the inner peripheral surface of the peripheral side wall and the outer surface of the inner wall.

49. (New) The semiconductor die carrier according to claim 48, further comprising a filler in the cavity to seal an interior of said housing.

50. (New) The semiconductor die carrier according to claim 49, wherein the filler comprises an adhesive.

51. (New) The semiconductor die carrier according to claim 49, further comprising a semiconductor die received on the end surface; and
the inner wall encircles the semiconductor die.

52. (New) The semiconductor die carrier according to claim 51, wherein the housing further comprises a plurality of spaced-apart ledges extending from the inner surface of the inner wall.

53. (New) The semiconductor die carrier according to claim 47, wherein the leads are arranged in multiple spaced apart rows.

54. (New) The semiconductor die carrier according to claim 47, wherein the plurality of leads each comprise a substantially L-shape.

55. (New) The semiconductor die carrier according to claim 47, wherein the peripheral side wall comprises a first material and the end surface comprises a second material different from the first material.